

ABSTRACT OF THE DISCLOSURE

APPARATUS FOR PARTIALLY REMOVING PLATING FILMS OF LEADFRAME

An apparatus for partially removing plating films of a leadframe includes a mask member having annular openings configured to coincide with the predetermined areas of the leadframe for which plating films are not required; a mask supporting means having outflow channels to introduce a film removing liquid, film removing liquid outflow holes, film removing liquid inflow channels, and an insoluble cathode wire housing groove; a mechanism for supplying a power to continuously run an insoluble cathode wire; and a mechanism for masking and dismasking the upper surface of the leadframe placed at a predetermined position of the mask supporting member. In this way, the plating films deposited outside an area for which plating is necessary are easily removed and cost can be reduced.

(FIG. 4)

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REPLACED

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